

Tech-X Corporation



Tech-X Corporation invites you to visit our booth (Booth #107) at the 18th IEEE International Pulsed Power Conference (<http://ppc.missouri.edu/>), June 19 - 23, at the Hyatt Regency, McCormick Place in Chicago.

We are proud to present the latest release of our electromagnetic plasma simulation software, VORPAL (<http://vorpal.txcorp.com>). VORPAL 4.2.2 includes improved documentation, simplified installation on all platforms, additional collision models, import of user-defined secondary electron yield data, a new photoemission model, delta-F particles for modeling tokamak geometries, and new field updaters.

Personnel from Tech-X will be participating in the following activities:

Posters (in the Regency Ballroom):

Monday, June 20

13:30 – 15:30

Microwave Posters I: Sources and Antennas, Slow Wave Devices, Systems

1P-40: Multipacting Simulations in a Coaxial Transmission Line with VORPAL, C. M. Roark, C. Nieter, P. H. Stoltz